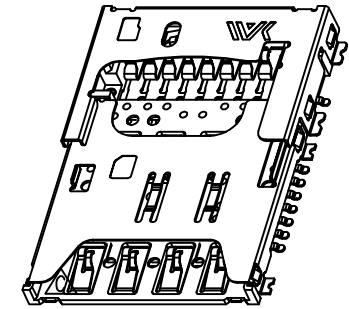
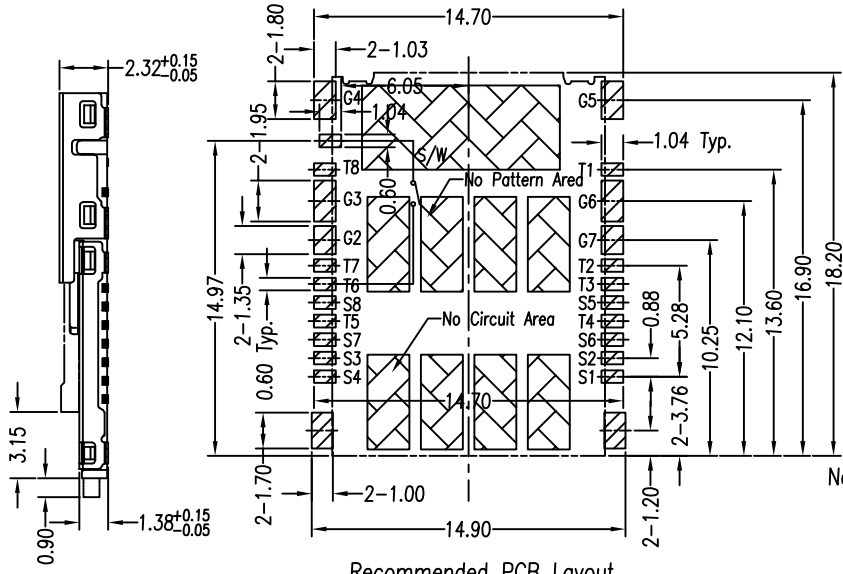
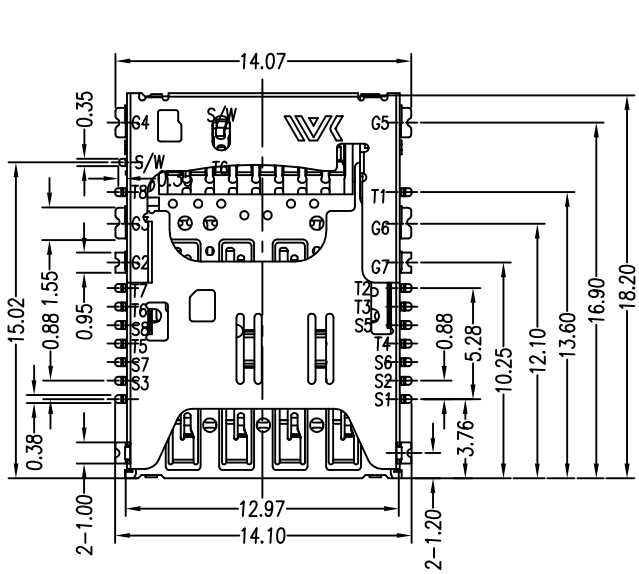
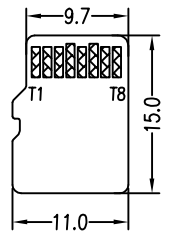
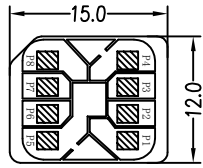
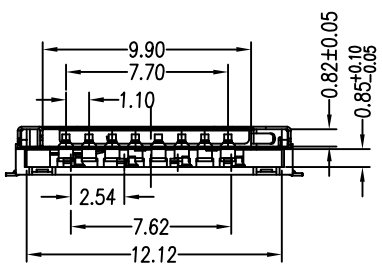


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
REV	ECNNO	LOCATIONS	DESCRIPTION	DATE	REVISER	



Note:
 1. Specification:
 1.1 Voltage Rating: 50V
 1.2 Current rating: 1 A Max.
 1.3 Dielectric withstanding voltage: 250 V(ac) for 1 min.
 1.4 Contact resistance: 50 mΩ Max.
 1.5 Insulation resistance: 1000 MΩ Min.
 1.6 Durability: 3000 Cycles
 1.7 Temperature range: -30°C~80°C

Recommended PCB Layout
 * 请开0.12mm或以上厚钢网



TF卡 Pin脚定义

No.	描述	Micro Sim卡 Pin脚定义	描述
T1	DAT2	8P	Vcc
T2	CD/DAT3	S1	RST
T3	CMD	S2	CLK
T4	VDD	S3	Reserved
T5	CLK	S4	GND
T6	VSS(GND)	S5	Vpp
T7	DAT0	S6	I/O
T8	DAT1	S7	Reserved
S/W	Card Detetion	S8	

TF卡状态	S/W端子	TF卡T6端子	S/W端子
卡未插入	打开		
卡插入	闭合		

4	Microsim-Shell	Sus201 T=0.12	50u"Min. Ni Plated all;1~3u"Min.Au plated on Solderetails
3	TF-Shell	Sus201 T=0.12	50u"Min. Ni Plated all;1~3u"Min.Au plated on Solderetails
2	Contact	C5210 T=0.10	50u"Min. Ni underplated all;1~3u"Min.Au plated Contact Area&Solderetails
1	Housing	LCP S475	UL 94V-0
No.	Name	Material	Finish
DWG NO: A-ST17-B08812-22		MATERIAL:	深圳市连欣科技有限公司
MODEL NO: MOLDNO.		FINISH:	
UNIT:	UNIT	SIZE: SIZE	
TOLERANCE UNSPECIFIED		DR: 陈国清	TITLE: 二合一(Micro Sim卡+TF卡.全贴)2.28H
.x	.X	CHK:	PART NO: XDST-B08812-22
.xx	.XX	APP:	REVISION: REV
.xxx	.XXX		SCALE: SCALE
ANG.	ANG.		SHEET: SHEET